

2. (Cancel) The mounting socket of claim 1, wherein the elastically deformable member comprises a spring.

3. (Cancel) The mounting socket of claim 1, wherein the elastically deformable member comprises a dish spring.

B2 4. (Amended) The mounting socket of claim 1, wherein the [elastically deformable member comprises:

a coil; and

a] conductive polymer is injected within the vias.

5. The mounting socket of claim 1, and further comprising:
a first adhesive layer affixed to the first side of the body.

6. The mounting socket of claim 5, and further comprising:
a polymer tape applied to the first adhesive layer;
a ground and power line circuit laid on the polymer tape; and
a second adhesive layer applied on and protecting the ground and power line circuit.

7. The mounting socket of claim 5, and further comprising:
a second adhesive layer affixed to the second side of the body.

8. (Cancel) The mounting socket of claim 1, and further comprising:
a push cover attachable to the socket body first and second sides.

B2 9. (Twice Amended) A method of mounting a socket to a board, the socket having a plurality of [solderless] elastically compressible [contact] conductive terminals, comprising:

applying an adhesive layer to a board side of the socket;

leveling the adhesive layer to make the adhesive layer substantially coplanar with the

[solderless compressible contact] terminals of the socket; and

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adhering the socket to the board compressing the plurality of [solderless compressible contact] terminals against complementary electrical contacts on the board, the terminals comprising a coil and a conductive polymer, the terminals adapted to exert a return force when compressed.

10. The method of claim 9, and further comprising:
applying a second adhesive layer to a package side of the socket opposite the board side of the socket; and
adhering a package to the second adhesive layer.

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11. (Twice Amended) A method of mounting a package to a board using a socket having [solderless] elastically compressible [contact] conductive terminals, the terminals comprising a coil and a conductive polymer, the terminals adapted to exert a return force when compressed, the method comprising:
applying a first adhesive layer to a first[,] package side of the socket;
leveling the first adhesive layer to make the adhesive layer substantially coplanar with the [solderless compressible contact] terminals;
adhering the package to the first adhesive layer compressing the terminals against complementary electrical contacts on the board, the terminals exerting a return force;
applying a second adhesive layer to a second[,] board side of the socket;
leveling the second adhesive layer to make the second adhesive layer substantially coplanar with the [solderless compressible contact] terminals; and
adhering the board to the second adhesive layer compressing the [solderless compressible contact] terminals against complementary electrical contacts on the board, the terminals exerting a return force.

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12. (Twice Amended) A [solderless] circuit interconnect, comprising:
a circuit board carrier having a plurality of through holes formed therein; and
a plurality of [solderless] elastically compressible conductive terminals with lands at each end, each terminal disposed in one of the through holes, wherein the terminals are adapted to be

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elastically compressible and exert a return force when compressed, each [conductive] terminal comprising [comprises an elastically deformable member] a coil and a conductive polymer.

13. The circuit interconnect of claim 12, and further comprising:
a first adhesive layer affixed to a first side of the circuit board carrier, the first layer having openings to expose the lands.

14. The circuit interconnect of claim 13, and further comprising:
a second adhesive layer affixed to a second side of the circuit board carrier, the second layer having openings to expose the lands, the second side opposite the first side.

15. (Cancel) The circuit interconnect of claim 12, wherein the conductive terminals are conductive rubber.

16. (Cancel) The circuit interconnect of claim 12, wherein the conductive terminals comprise a spring.

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17. (Amended) The circuit interconnect of claim 12, wherein the [conductive terminals comprise:

a compressible coil; and

a] conductive polymer is injected within the vias.

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18. (Twice Amended) A circuit package, comprising:

a substrate having a plurality of [solderless] conductive terminals therethrough, the terminals comprising a coil and a conductive polymer, the terminals adapted to be elastically compressible and to exert a return force when compressed;

a first adhesive layer affixed to a first side of the substrate; and

a package affixed to the first adhesive layer.

19. The circuit package of claim 18, and further comprising:
a second adhesive layer affixed to a second side of the substrate, the second side opposite the first side.

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20. (Twice Amended) An integrated circuit, comprising:
a substrate having a plurality of vias therein; and
a plurality of elastically compressible [deformable solderless] terminals, the terminals comprising a coil and a conductive polymer, the terminals adapted to exert a return force when compressed, each terminal positioned in a via.

21. (Twice Amended) A circuit assembly, comprising:
a substrate having a built-in socket, the socket having a plurality of vias therein;
a plurality of elastically compressible [deformable, solderless] conductive terminals, the terminals comprising a coil and a conductive polymer, the terminals adapted to exert a return force when compressed, each terminal disposed within a via; and
a circuit board having a plurality of mounting areas, the mounting areas disposed in a plurality of interconnected planes which are substantially non-planar with each other[; and],
wherein each terminal is individually [deformable] compressible to contact its respective mounting area at the plane of the mounting area.

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22. (Amended) A circuit assembly, comprising:
a microprocessor;
a substrate having a built-in socket having a plurality of vias therein, and a plurality of conductive[,] elastically compressible [deformable solderless] terminals, the terminals are adapted to exert a return force when compressed, the terminals comprising a coil and a conductive polymer, at least a portion of [the plurality of terminals] each terminal disposed within a via; and
a motherboard having a plurality of mounting areas thereon, wherein each [elastically deformable] terminal is compressed [deformed] to contact a mounting area.